

DESCRIPTION

POLISHING APPARATUS

TECHNICAL FIELD

[0001]

The present invention relates to a polishing apparatus, particularly to a polishing apparatus provided with wafer-detecting sensors.

BACKGROUND ART

[0002]

Single side polishing of a wafer is performed by using a polishing apparatus composed of a turn table having a polishing pad attached thereto, a polishing agent supply mechanism for supplying a polishing agent onto the polishing pad, a polishing head for holding a wafer, etc. These apparatus polish a wafer by holding the wafer with the polishing head, supplying the polishing agent onto the polishing pad from the polishing agent supply mechanism, and bringing the surface of the wafer into sliding contact with the polishing pad while rotating each of the turn table and the polishing head (see Patent Document 1, for example).

[0003]

In polishing a wafer with a polishing apparatus described above, the wafer sometimes comes off from the polishing head. In some cases, the polished wafer is left on the turn table due to a mistake in picking up. In order to detect these, polishing apparatuses are provided with a wafer-detecting sensor(s).

[0004]

The wafer-detecting sensor is provided with